11th Annual International Wafer-Level Packaging Conference

(IWLPC 2014)

San Jose, California, USA
11-13 November 2014

ISBN: 978-1-5108-0356-5

Printed from e-media with permission by:

Curran Associates, Inc.
57 Morehouse Lane
Red Hook, NY 12571

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Printed by Curran Associates, Inc. (2015)

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Edina, MN 55424

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Sessions at a Glance: Tuesday, November 11th

7:50 AM	**Opening Comments** Keith Cooper, SET North America, Conference General Chair **Oak Ballroom (2nd Floor)**		
8:00 AM	**Keynote Address: Living Connected Through Trillions Sensors ..... 1** Janusz Bryzek, Ph.D., Chair of the TSensors Summit **Oak Ballroom (2nd Floor)**		
9:00 AM	**Coffee Break** **Exhibit Hall**		
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	Session 1 – Wafer-Level Final Test & Simulation Chair: Janet Love, Blair-Gordon Associates Co-Chair: Rey Alvarado, Qualcomm	**Session 2 – Temporary Wafer Bonding Integration and Underfill** Chair: Peter Ramm, Ph.D., Fraunhofer EMFT Co-Chair: Ted Tessier, FlipChip International	**Session 3 – 3D MEMS Interconnects and Bonding** Chair: Roger Grace, Roger Grace Associates Co-Chair: Russell Shumway, Amkor Technology
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11:45 AM	**Lunch Break – Sponsored By Johnstech International** **Bayshore Foyer**		
1:15 PM	**3D PANEL DISCUSSION - HOSTED BY 3D INCITES, INC.** **OAK BALLROOM (2ND FLOOR)** **System Level Advantages of 3D Integration** **Moderator:** Francoise von Trapp, 3D InCites, Inc. **Panelists:** Rama Alapati, Global Foundries, E. Jan Vardaman, TechSearch International Inc, Mike Gianfagna, eSilicon, Bel Haba, Google Simon McElrea, Energous Corporation		
2:45 PM	**Refreshment Break – Sponsored by Axus Technology** **Exhibit Hall**		
	WLP TRACK | MONTEREY ROOM	**3D TRACK | SAN CARLOS ROOM**	**MEMS TRACK | SANTA CLARA**
	Session 4 - Wafer-Level Materials Chair: Luu Nguyen, Ph.D., Texas Instruments Co-Chair: Boyd Rogers, Ph.D., Deca Technologies	**Session 5 – Bonding and Metrology** Chair: Sumant Sood, KLA-Tencor Co-Chair: Keith Cooper, SET Corporation	**Session 6 - MEMS Wafer Level Packaging** Chair: Maaike M. Visser Taklo, Ph.D., SINTEF Co-Chair: Russell Shumway, Amkor Technology
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	2:15pm– 3:00pm, Exhibit Hall **Refreshment Break – Sponsored by Johnstech International**		
	Exhibition Closes 3:30pm		
	WLP TRACK | MONTEREY ROOM	**3D TRACK | SAN CARLOS ROOM**	**3D-I TRACK | SANTA CLARA ROOM**
	Session 10 - Fan-Out Wafer and Panel-Level Packaging Technologies Chair: Curtis Zwenger, Amkor Technology Co-Chair: Rey Alvarado, Qualcomm	**Session 11 – Electroplating and Metrology** Chair: Steven Xu, Qualcomm Co-Chair: André Rouzaud, CEA LETI	**Session 12 – Integration** Chair: Laurette Nacamulli, The Dow Chemical Company Co-Chair: Keith Cooper, SET Corporation
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